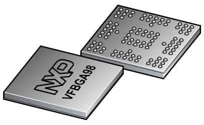


SOT1982-1

VFBGA98, very thin fine-pitch ball grid array package, 98 terminals, 0.5 mm pitch, 7 mm x 7 mm x 0.86 mm body

1 October 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA98
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	26-09-2018
Manufacturer package code	98ASA01278D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
seated height	-	0.86	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	98	-	

2 Package outline

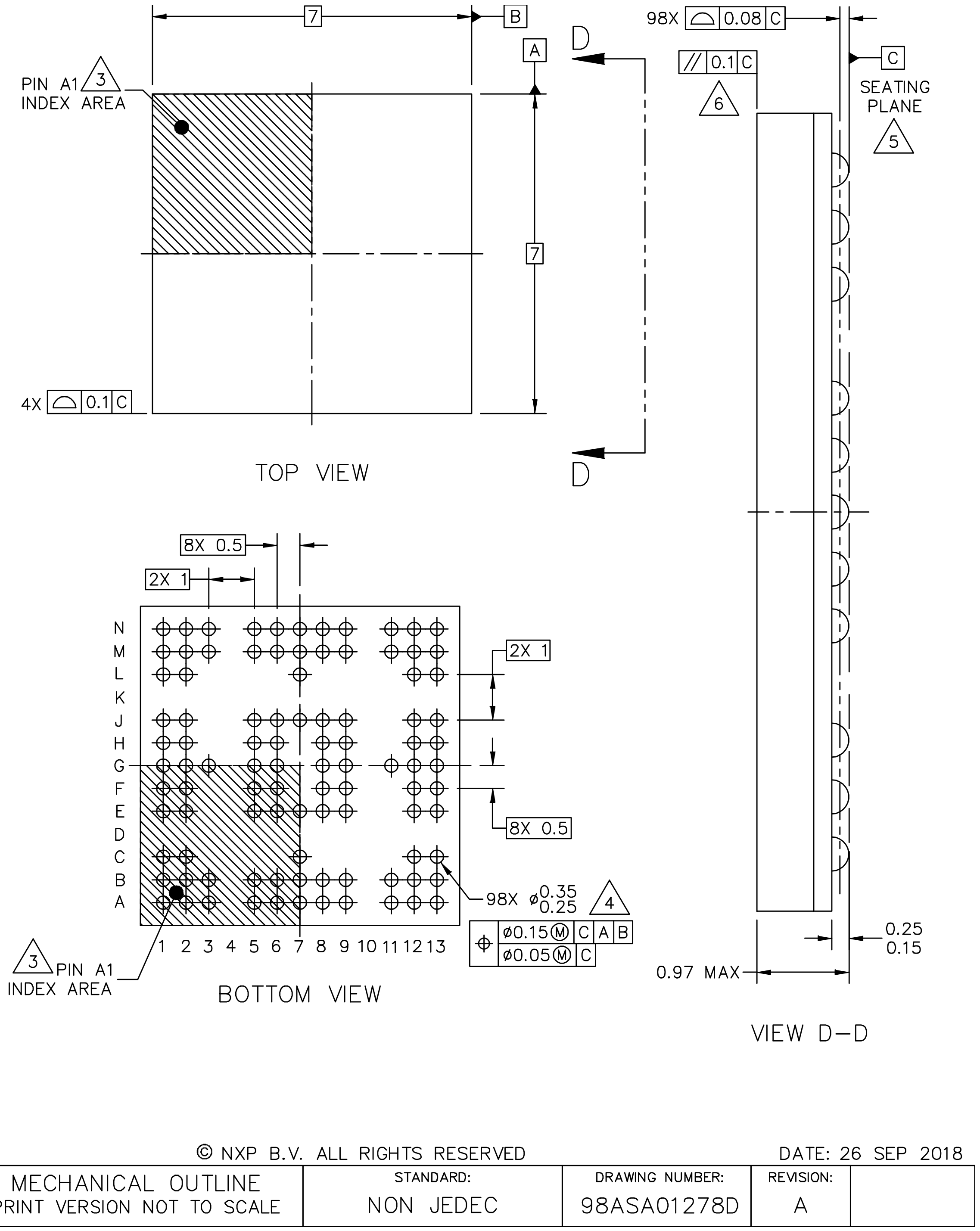
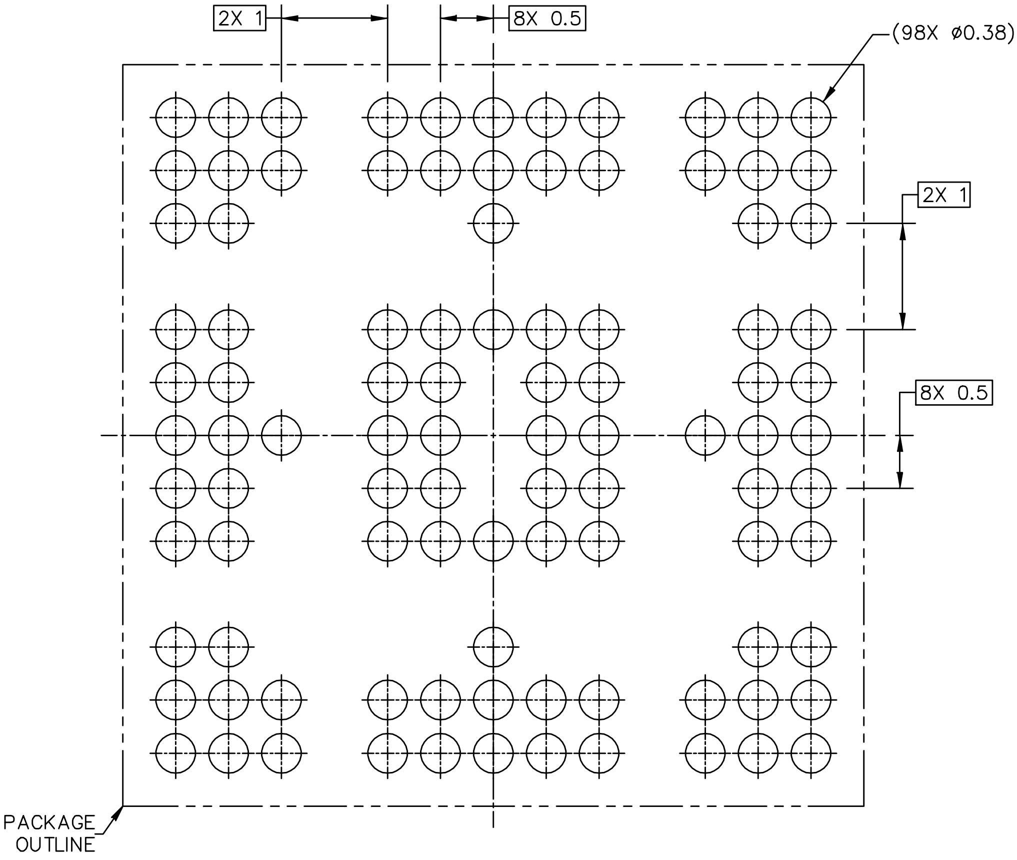


Figure 1. Package outline VFBGA98 (sot1982-1)

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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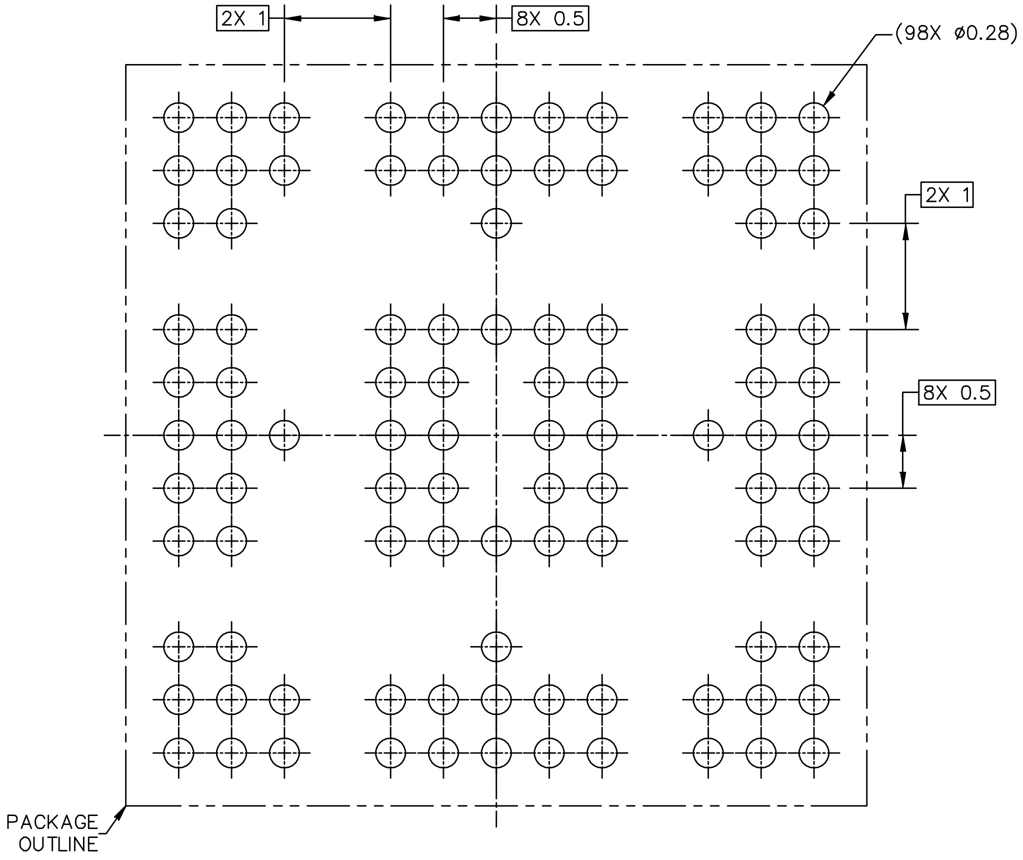
DATE: 26 SEP 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01278D	REVISION: A	

Figure 2. Reflow soldering footprint part1 for VFBGA98 (SOT1982-1)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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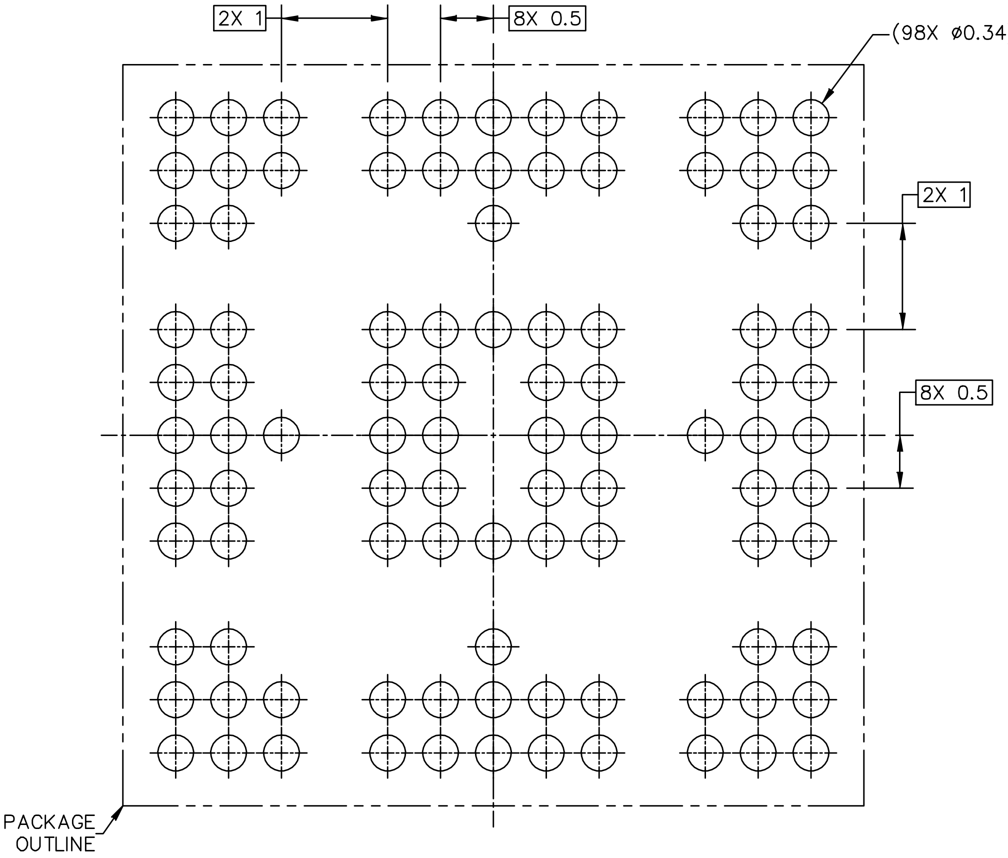
DATE: 26 SEP 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01278D	REVISION: A	

Figure 3. Reflow soldering footprint part2 for VFBGA98 (SOT1982-1)



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 26 SEP 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01278D	REVISION: A	

Figure 4. Reflow soldering footprint part3 for VFBGA98 (SOT1982-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

DATE: 26 SEP 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01278D	REVISION: A	

Figure 5. Package outline note VFBGA98 (sot1982-1)

4 Legal information

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